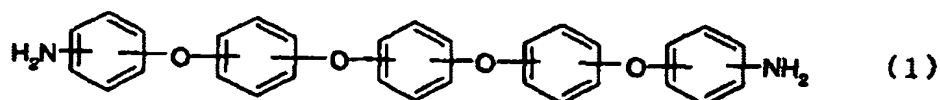




ABSTRACT

The adhesive resin of the invention comprises a polyimide resin obtained by reacting a diamine component containing the compound (1) as an essential component with a tetracarboxylic dianhydride component.



The diamine component contains a silicone diamine having a specific structure and/or the tetracarboxylic dianhydride component contains a silicone acid dianhydride having a specific structure. Film adhesives made by using the adhesive resin preferably together with a thermosetting resin, and, if necessary, an inorganic filler are excellent in low-temperature adhesion, resistance to moisture absorption, heat resistance, and workability in adhesive adhering and are favorably usable as semiconductor-mounting materials for adhering semiconductor elements to substrates.